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DEC 01 2003

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Hou, *et al.* Docket No.: TSM03-0151  
Serial No.: 10/691,019 Art Unit: TBD  
Filed: October 22, 2003 Examiner: TBD  
For: Method of Forming a Contact on a Silicon-on-Insulator Wafer

**Certificate of Mailing via First Class Mail (37 C.F.R. § 1.8(a))**

Date of Deposit: November 24, 2003

I hereby certify that the below listed correspondence is being deposited with the United States Postal Service on the date indicated above as first class mail in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450.

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Respectfully submitted,



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